

SN54ABT646, SN74ABT646 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS068E – JULY 1991 – REVISED JULY 1994

- State-of-the-Art *EPIC-II B™* BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Drive Outputs (–32-mA I_{OH} , 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT646.

Output-enable ($\overline{OE}$) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus will receive data when $\overline{OE}$ is low. In the isolation mode ($\overline{OE}$ high), A data may be stored in one register and/or B data may be stored in the other register.

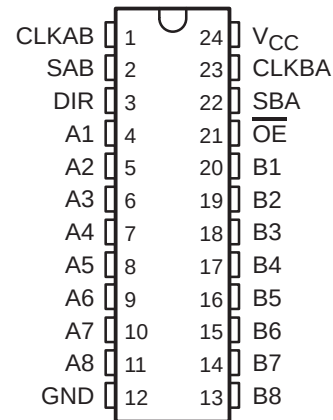
When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

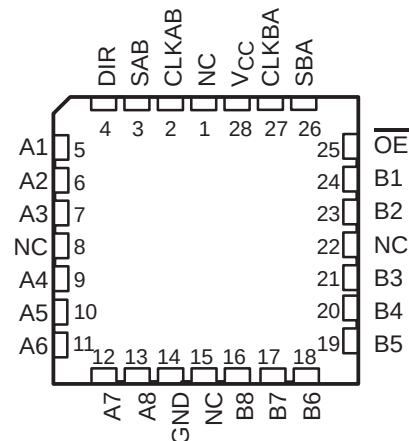
The SN74ABT646 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT646 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT646 is characterized for operation from -40°C to 85°C .

SN54ABT646 . . . JT PACKAGE
SN74ABT646 . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT646 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

EPIC-II B is a trademark of Texas Instruments Incorporated.

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 **TEXAS
INSTRUMENTS**

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SN54ABT646, SN74ABT646

OCTAL BUS TRANSCEIVERS AND REGISTERS

WITH 3-STATE OUTPUTS

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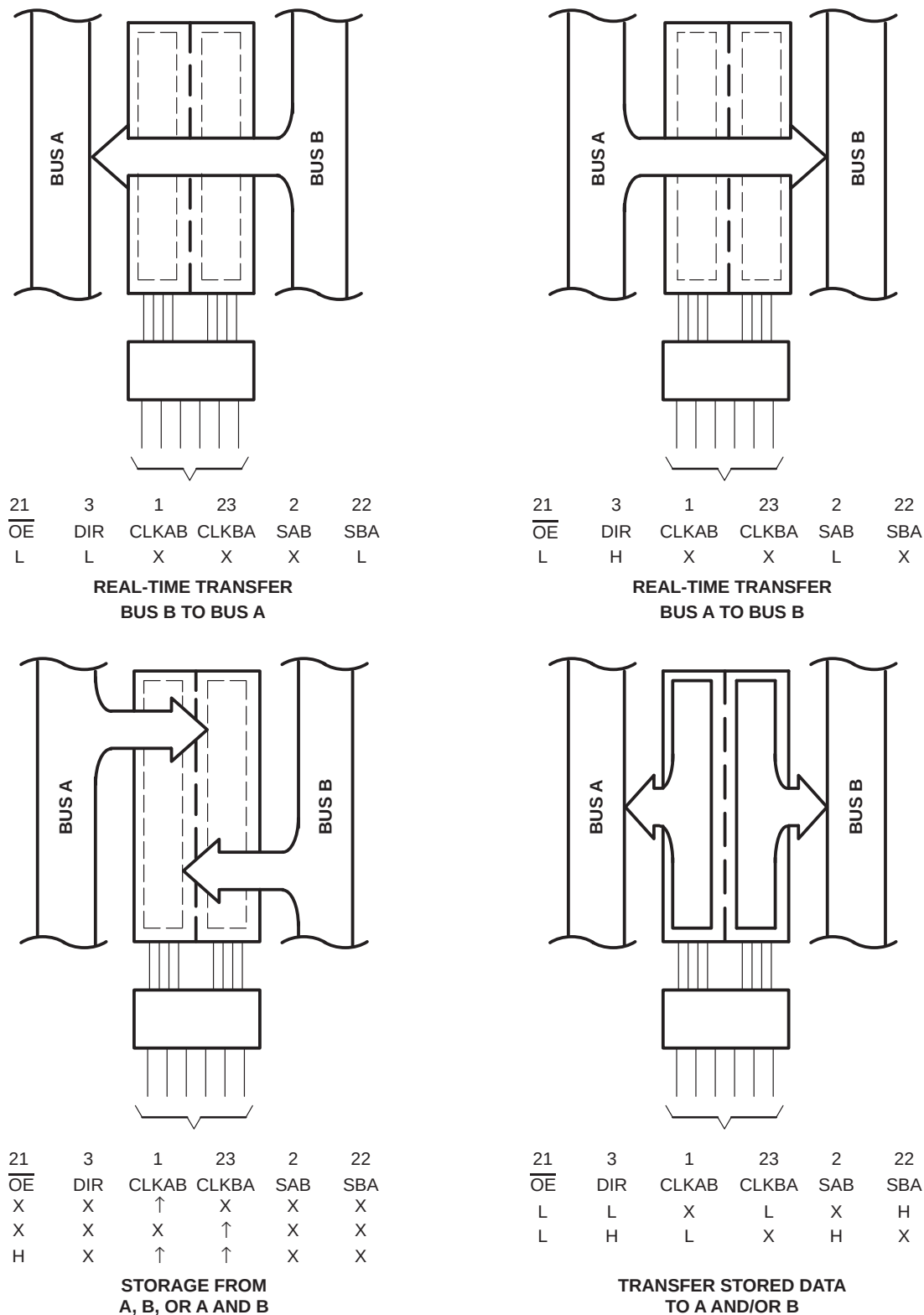


Figure 1. Bus-Management Functions

Pin numbers shown are for DB, DW, JT, NT, and PW packages.

SN54ABT646, SN74ABT646

OCTAL BUS TRANSCEIVERS AND REGISTERS

WITH 3-STATE OUTPUTS

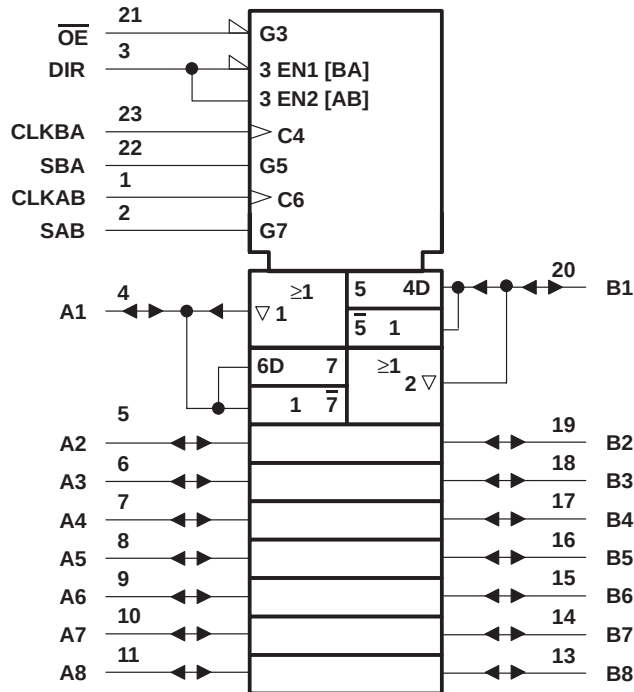
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FUNCTION TABLE

INPUTS						DATA I/Os		OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
X	X	↑	X	X	X	Input	Unspecified [†]	Store A, B unspecified [†]
X	X	X	↑	X	X	Unspecified [†]	Input	Store B, A unspecified [†]
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	H or L	H or L	X	X	Input disabled	Input disabled	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
L	H	X	X	L	X	Input	Output	Real-time A data to B bus
L	H	H or L	X	H	X	Input	Output	Stored A data to B bus

[†] The data output functions may be enabled or disabled by various signals at the OE and DIR inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every low-to-high transition of the clock inputs.

logic symbol[‡]



[‡] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, and PW packages.

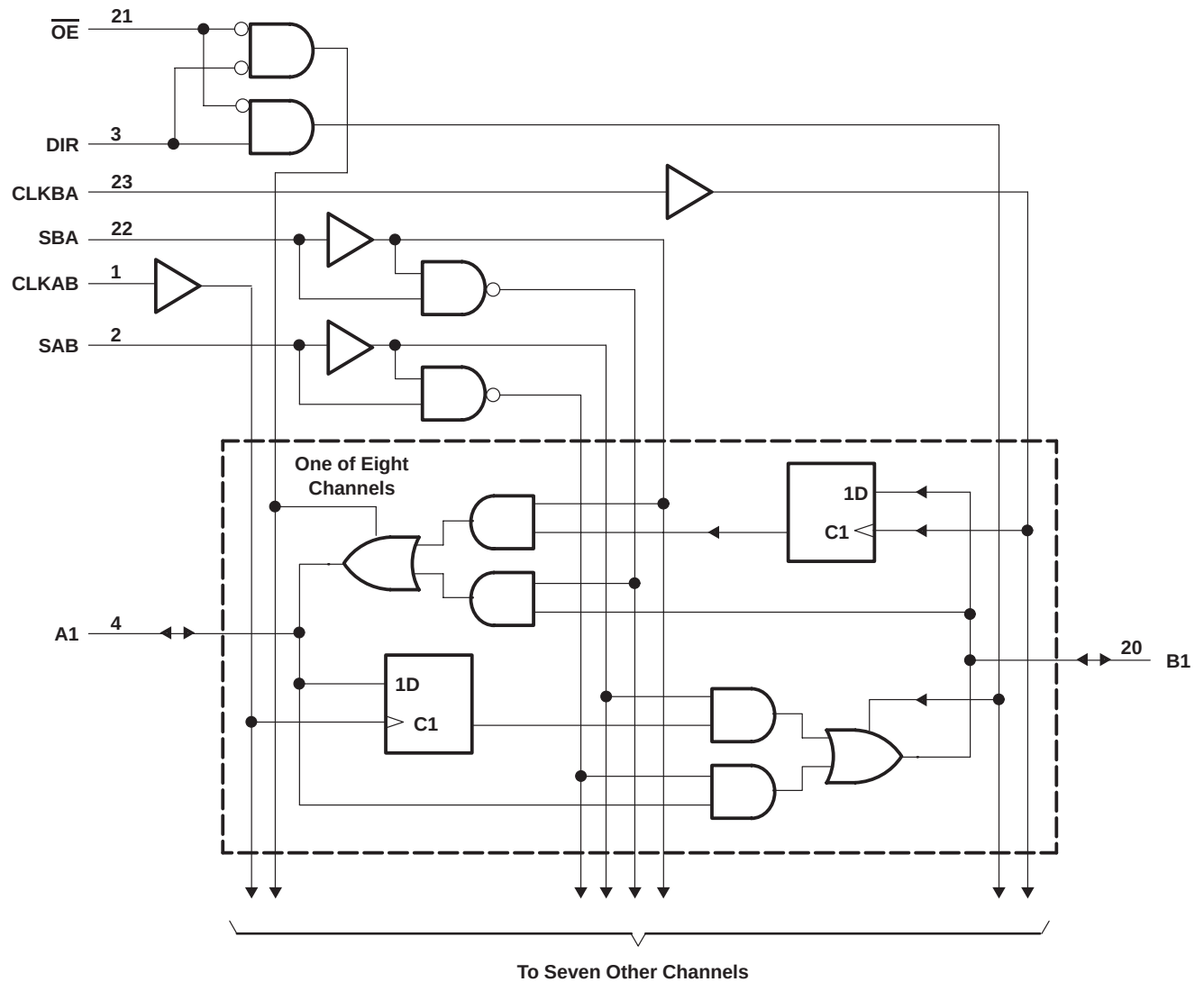
SN54ABT646, SN74ABT646

OCTAL BUS TRANSCEIVERS AND REGISTERS

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logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and PW packages.

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OCTAL BUS TRANSCEIVERS AND REGISTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT646	96 mA
SN74ABT646	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DB package	0.65 W
DW package	1.7 W
NT package	1.3 W
PW package	0.7 W
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ABT646		SN74ABT646		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.

SN54ABT646, SN74ABT646

OCTAL BUS TRANSCEIVERS AND REGISTERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C			SN54ABT646		SN74ABT646		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA				–1.2		–1.2		–1.2	V
V _{OH}	V _{CC} = 4.5 V, I _{OH} = –3 mA		2.5			2.5		2.5		V
	V _{CC} = 5 V, I _{OH} = –3 mA		3			3		3		
	V _{CC} = 4.5 V	I _{OH} = –24 mA	2			2				
		I _{OH} = –32 mA	2*					2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
		I _{OL} = 64 mA			0.55*				0.55	
I _I	V _{CC} = 5.5 V, V _I = V _{CC} or GND	Control inputs			±1		±1		±1	μA
		A or B ports			±100		±100		±100	
I _{OZH} ‡	V _{CC} = 5.5 V, V _O = 2.7 V				10 [§]		50		10 [§]	μA
I _{OZL} ‡	V _{CC} = 5.5 V, V _O = 0.5 V				–10 [§]		–50		–10 [§]	μA
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V				±100				±100	μA
I _{CEX}	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μA
I _O ¶	V _{CC} = 5.5 V, V _O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high			250		250		250	μA
		Outputs low			30		30		30	mA
		Outputs disabled			250		250		250	μA
ΔI _{CC} #	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5	mA
C _i	V _I = 2.5 V or 0.5 V	Control inputs			7					pF
C _{io}	V _O = 2.5 V or 0.5 V	A or B ports			12					pF

* On products compliant to MIL-STD-883, Class B, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ This data sheet limit may vary among suppliers.

¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		V _{CC} = 5 V, T _A = 25°C		SN54ABT646		SN74ABT646		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	0	125	0	125	0	125	MHz
t _w	Pulse duration, CLK high or low	4		4		4		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	High	3.5	3.5		3.5		ns
		Low	3	3		3		
t _h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		0		ns

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$			SN54ABT646		SN74ABT646		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			125					125		MHz
t_{PLH}	CLKBA or CLKAB	A or B	2.2	4	6.8			2.2	7.8	ns
t_{PHL}			1.7	4	7.4			1.7	8.4	
t_{PLH}	A or B	B or A	1.5	3	5.9			1.5	6.9	ns
t_{PHL}			1.5	3.3	5.9			1.5	6.9	
t_{PLH}	SAB or SBA [†]	B or A	1.5	4	6.1			1.5	7.1	ns
t_{PHL}			1.5	3.6	6.9			1.5	7.9	
t_{PZH}	$\overline{OE}$	A or B	1	4.3	5.3			1	6.3	ns
t_{PZL}			2.1	5.8	7.4			2.1	8.8	
t_{PHZ}	$\overline{OE}$	A or B	1.5	3.5	7.3			1.5	8.3	ns
t_{PLZ}			1.5	3	7			1.5	7.5	
t_{PZH}	DIR	A or B	1.2	4.5	5.7			1.2	6.7	ns
t_{PZL}			2.5	6.5	9			2.5	9.5	
t_{PHZ}	DIR	A or B	1.5	3.8	6.7			1.5	7.7	ns
t_{PLZ}			1.5	3.8	7.2			1.5	8.2	

[†] These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

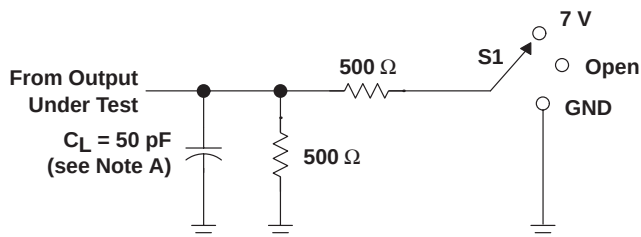
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OCTAL BUS TRANSCEIVERS AND REGISTERS

WITH 3-STATE OUTPUTS

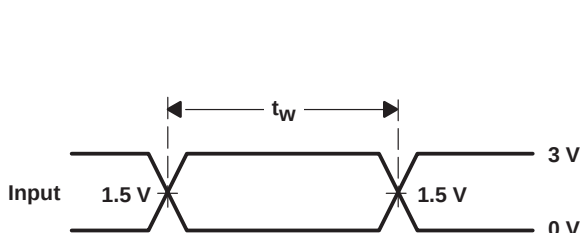
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PARAMETER MEASUREMENT INFORMATION

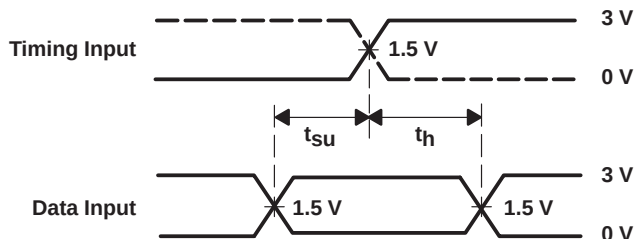


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

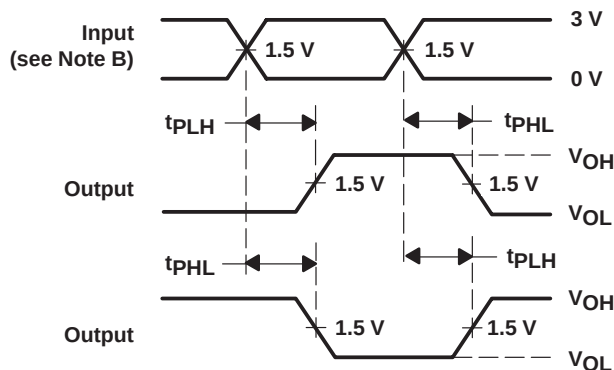
LOAD CIRCUIT FOR OUTPUTS



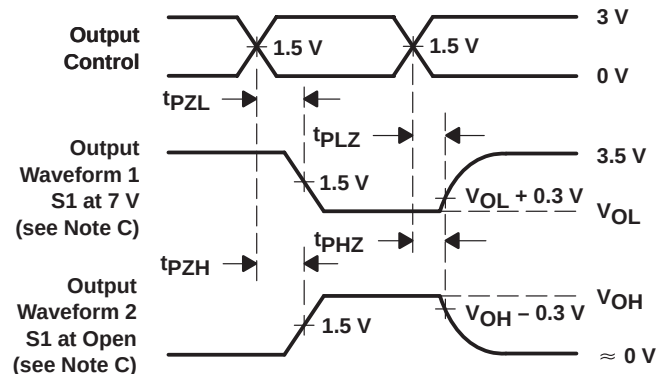
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74ABT646DBR	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB646
SN74ABT646DBR.B	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB646
SN74ABT646DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT646
SN74ABT646DW.B	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT646
SN74ABT646DWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT646
SN74ABT646DWR.B	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT646
SN74ABT646PW	Active	Production	TSSOP (PW) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB646
SN74ABT646PW.B	Active	Production	TSSOP (PW) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB646
SN74ABT646PWR	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB646
SN74ABT646PWR.B	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB646

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

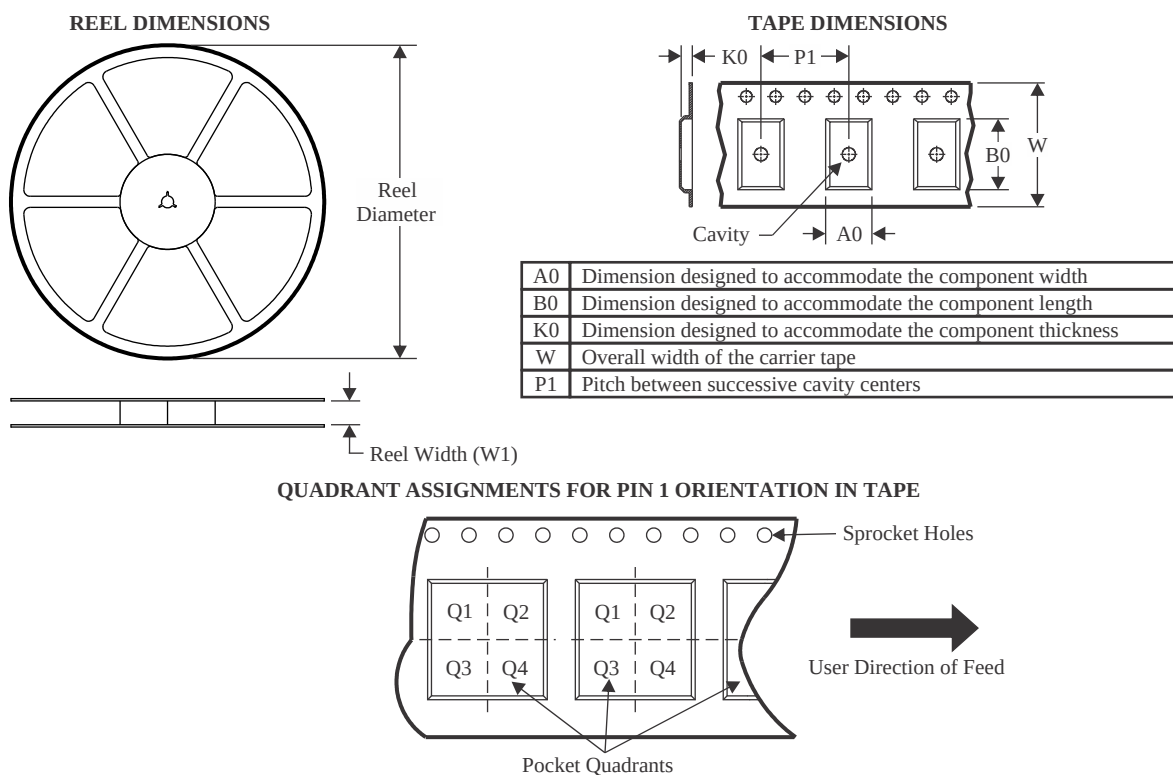
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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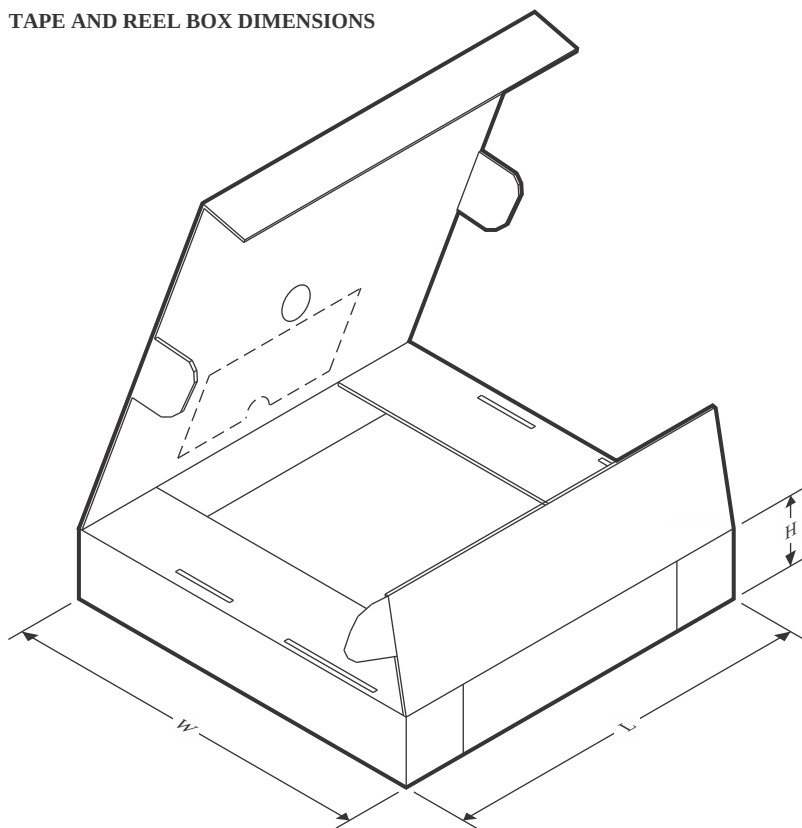
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT646DBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT646DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT646PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

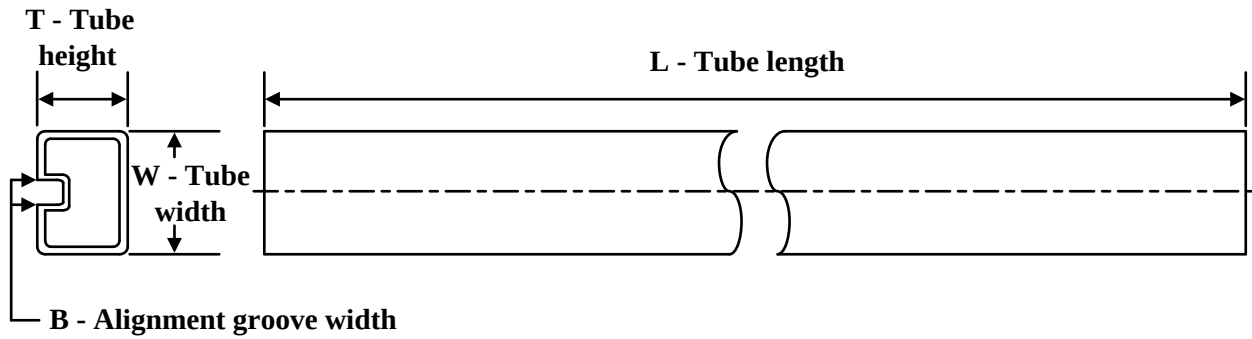
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT646DBR	SSOP	DB	24	2000	353.0	353.0	32.0
SN74ABT646DWR	SOIC	DW	24	2000	350.0	350.0	43.0
SN74ABT646PWR	TSSOP	PW	24	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ABT646DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT646DW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT646PW	PW	TSSOP	24	60	530	10.2	3600	3.5
SN74ABT646PW.B	PW	TSSOP	24	60	530	10.2	3600	3.5



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



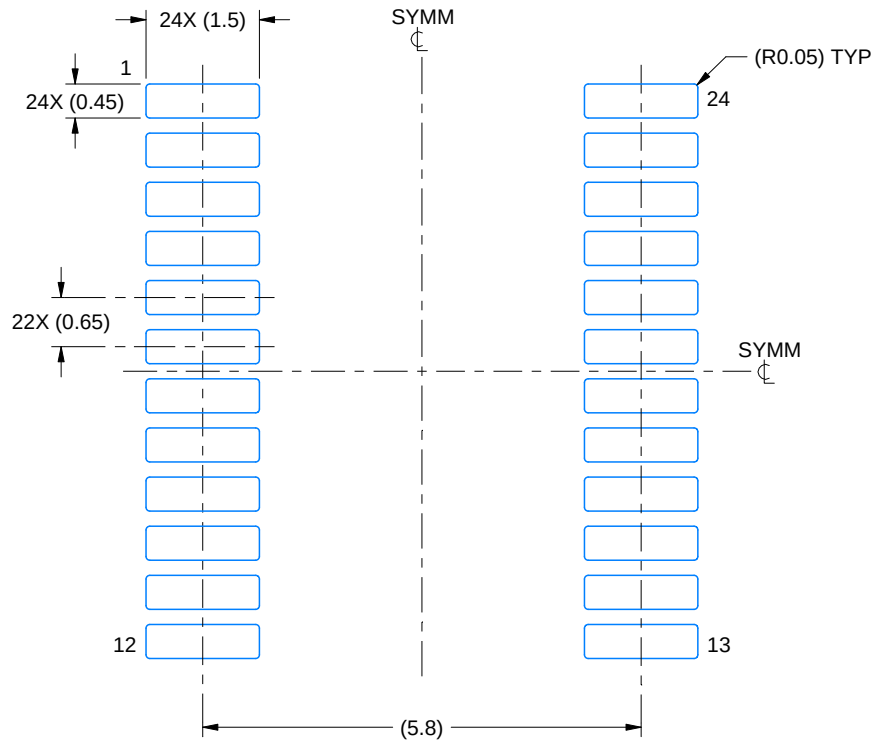
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

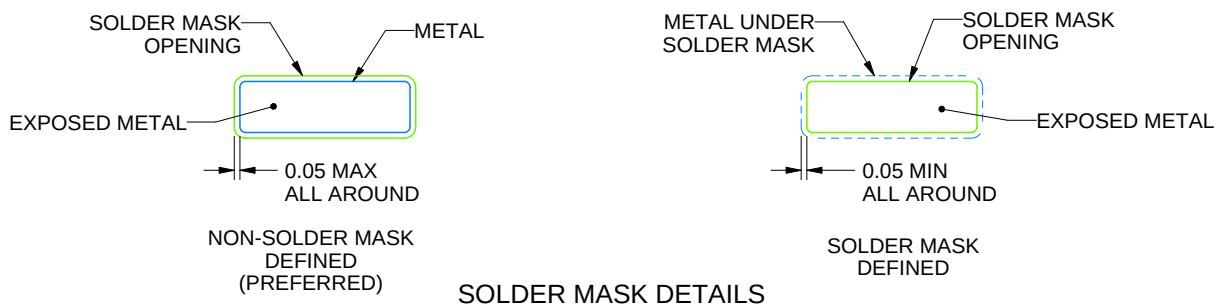
PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

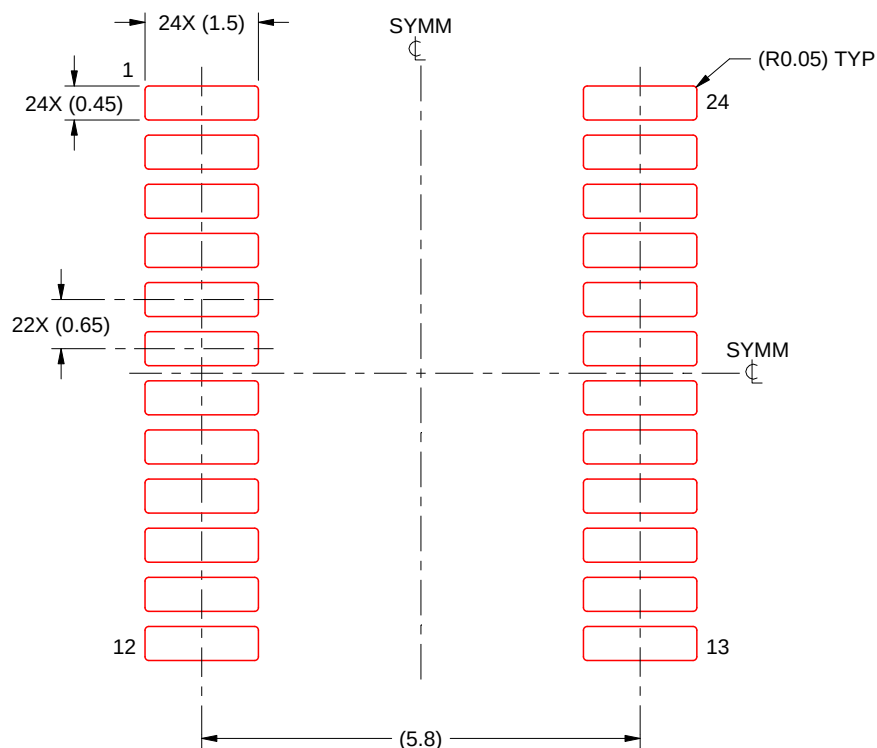
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

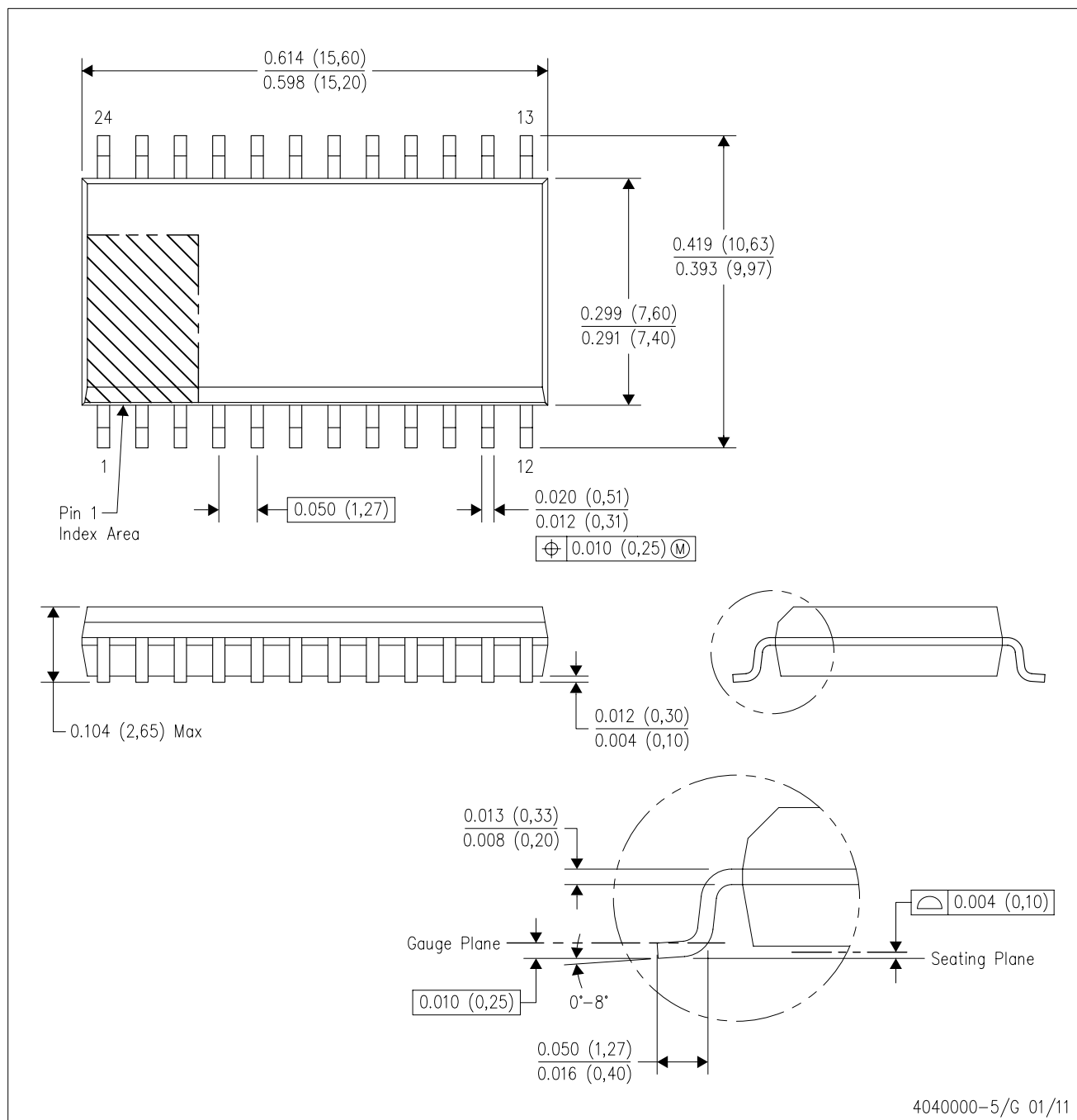
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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

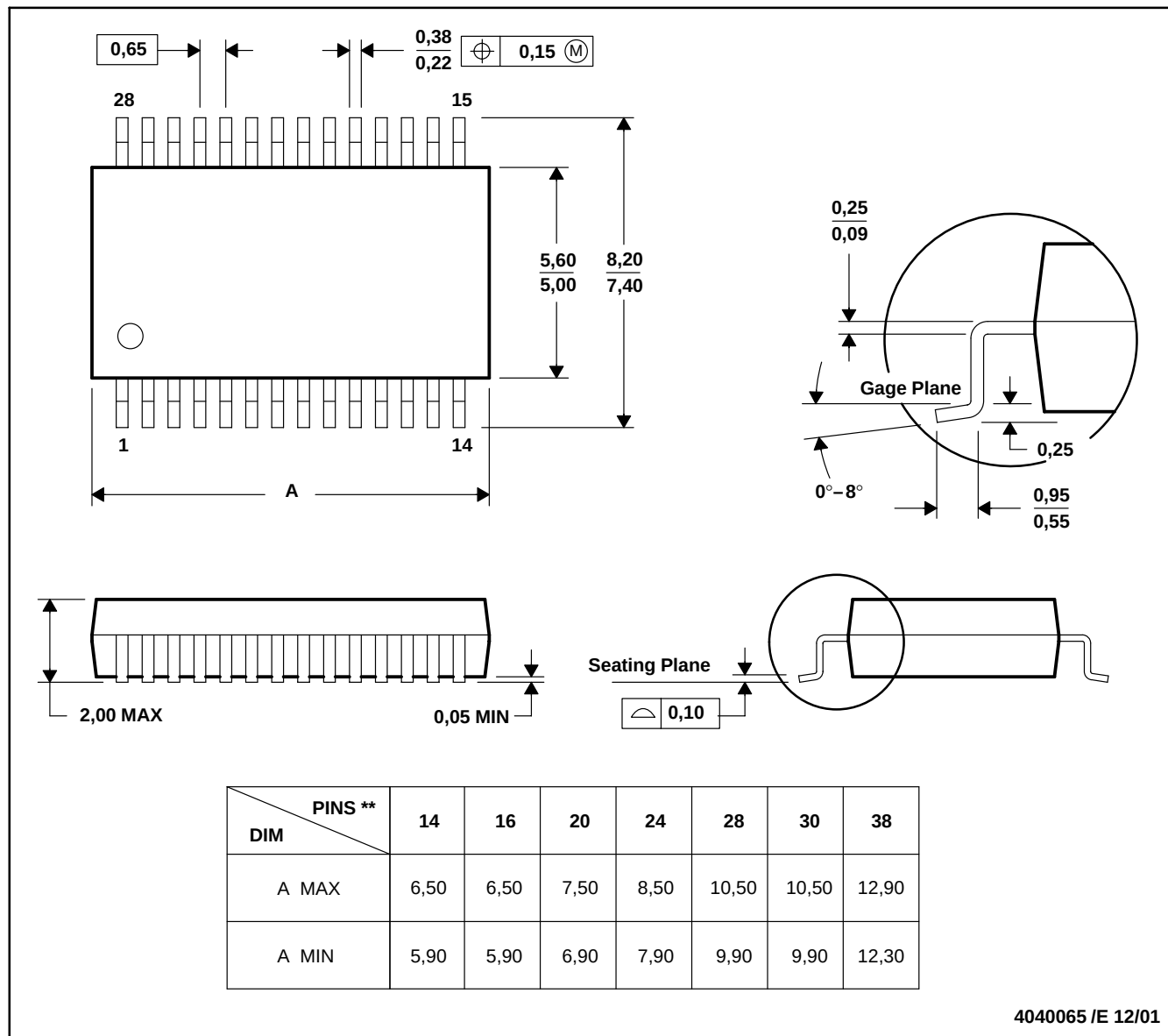


- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AD.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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